Hi-Fi B350S1 Motherboard

- Support AMD Ryzen CPU / APU
- AMD B350 single chip architecture
- Support 2-DIMM DDR4-3200(OC)/ 2933(OC)/ 2667/ 2400 up to 32G maximum capacity
- BIOSTAR Hi-Fi Technology inside
- Support DVI-D
- Support USB 3.1 Gen1

Specifcation

CPU SUPPORT	Supports AMD AM4 Socket for 3rd, 2nd and 1st Gen Ryzen/2nd and 1st Gen Ryzen with Radeon Vega Graphics/Athlon with Radeon Vega Graphics/7th Gen A-Series/Athlon X4 Processors
MEMORY	Support Dual Channel DDR4 3200(OC)/ 2933(OC)/ 2667/ 2400/ 2133/ 1866 MHz Support Non-ECC & ECC Un-buffered DIMM Memory modules 2 x DDR4 DIMM Memory Slot Max. Supports up to 32GB Memory * DDR4 2667 for AMD Ryzen CPU Ryzen - DDR Maximum Frequency Support Table(For better DDR4 compatibility, it is recommended to follow the table below to install DDR4 modules. Please refer to memory support list for more details.) Maximum / DIMMA1 / DIMMB1 DDR4-2667 / SR / - DDR4-2667 / DR / - DDR4-2667 / SR / SR DDR4-2400 / DR / DR SR:Single-rank DIMM, 1R x4 or 1R x8 DR:Dualrank DIMMs, 2R x4 or 2R x8
INTEGRATED VIDEO	By CPU model Supports DX12 Supports HDCP
STORAGE	4 x SATA III Connector Support SATA RAID: 0,1,10
LAN	Realtek RTL8111H - 10/100/1000Mb/s Controller Support Super LAN Surge Protection
AUDIO CODEC	Realtek ALC887 8-Channel HD Audio Support Biostar Hi-Fi

USB	4 x USB 3.1 Gen1 Port 1 x USB 3.1 Gen1 Header 2 x USB 2.0 Port 2 x USB 2.0 Port(only 5V power, up to 1.5A) 2 x USB 2.0 Header
EXPANSION SLOT	1 x PCI-E 3.0 x16 Slot(x16 for Ryzen CPU only, NPU/APU run at x8 speed) 2 x PCI-E 3.0 x1 Slot
REAR I/O	1 x PS/2 Mouse 1 x PS/2 Keyboard 4 x USB 3.1 Gen1 Port 2 x USB 2.0 Port 2 x USB 2.0 Port(only 5V power, up to 1.5A) 1 x DVI-D Connector, resolution up to 1920 x 1200 @60Hz 1 x LAN Port 3 x Audio Jacks
INTERNAL I/O	1 x USB 3.1 Gen1 Header 2 x USB 2.0 Header 4 x SATA III Connector (6Gb/s) 1 x SATA Power Connector(for rear USB power enhancement) 1 x Front Audio Header 1 x Front Panel Header 1 x CPU Fan Connector 1 x System Fan Connector 1 x COM Port Header
H/W MONITORING	CPU / System Temperature Monitoring CPU / System Fan Monitoring Smart / Manual CPU / System Fan Control System Voltage Monitoring
DIMENSION	Micro ATX Form Factor Dimension: 22.6cm x 19.8cm (W x L)
OS SUPPORT	Supports Windows 10(x64) / 11(x64) Support Windows 7 (x64) for Bristol / Summit /Pinnacle Ridge only
BUNDLE SOFTWARE	BullGuard Smart Ear headphone Utility Smart Speed LAN(Windows 7 only)
ACCESSORIES	2 x SATA Cable 1 x I/O Shield 1 x DVD Driver 1 x Quick Guide
FEATURES	Supports PURO Hi-Fi Supports 100% Solid capacitor BIO-FLASHER Supports BIOS Online Update

OVERVIEW

AMD SOCKET AM4 B350	**AMD B350 chipset** AMD B350 is the mainstream chipset and offers the most value in terms of I/O and functionality.
RYZEN	**AMD AM4 Ryzen CPU support** AMD's new AM4 platform will accompany Ryzen. It brings all of the new tech that you'd expect, including DDR4 RAM, PCI-E Gen 3, USB 3.1 Gen 2, NVMe and SATA Express.

	Hi-Fi A combination of exclusive hardware & software design including "ground-isolation circuit design","an independent audio power", and "a built=on-board amplifier", with all these hardware features gives you the best audio quality and performance. As for software, we offer you a free bundle utility "Multi-Channel Calibration" which normally you'll find in high level sound systems; this feature allows you to auto detect your location; with a user friendly interface, you can easily adjust the volume of every speakers to make a well balanced surround sound. And of course, the built-on-board amplifier always gives you a super powerful sound comparing to other motherboards.
	HD Audio Provides high quality sound with minimal loss of audio fidelity.
	Hi-Fi Power Audio power is an important factor in audio quality. Most AV equipment isolates the power supply for each analog and digital signal to gather high-quality sound reproduction. Equipped with BIOSTAR Hi-Fi Power technology, it will utilize audio components with independent power design for a significant reduction in electronic noise and superb sound quality.
	Hi-Fi Ground BIOSTAR Hi-Fi Ground (Golden Line) is noise-blocking multi-layer PCB design to isolates analog audio signals from digital sources. Unique PCB layout is ideal for exceptional clarity and high fidelity sound.
	Hi-Fi AMP The built-in amplifier can drive major high-end headphones with over 100dB loads and offer wide band-width, low noise, high slew rate and low distortion audio source from front panel I/O. Gaming enthusiasts can enjoy a fuller range of dynamic sound with crisper details and less distortion.
	Smart Ear Smart EAR is a windows-based audio utility which allows you to easily adjust system volume. With its user-friendly GUI, you can also increase or decrease impedance setting (Low/High Gain) to optimize your headphone performance. You can easily enjoy high-quality and awesome sound.
	Hi-Fi Resistor Metal-oxide film resistors are made of metal oxides such as tin oxide. The electric characteristics are greater stability and reliability than regular metal film resistors when operating in an extremely broad working temperature range. This special component is used in applications with high endurance audio demands.
	Hi-Fi Cap BIOSTAR Hi-Fi series motherboards come with high quality ‘Non-Polarized Electrolysis Electric audio capacitors’ for each audio channel circuit. The customized audio capacitors deliver low noise, low distortion, and wide bandwidth to achieve the highest sound resolution and sound expansion. The critical component will ensure the most realistic sound effects to gaming enthusiasts.

	DVI DVI is better than VGA for LCD displays since it is digital while VGA is analog. For LCD displays, the picture is digitized pixel per pixel. Through DVI, the panel gets data for each pixel, so the picture generated in the Graphics device matches the pixels on the panel itself.
	DX12 DirectX 12 introduces the next version of Direct3D, the graphics API at the heart of DirectX. Direct3D is one of the most critical pieces of a game or game engine, and we've redesigned it to be faster and more efficient than ever before. Direct3D 12 enables richer scenes, more objects, and full utilization of modern GPU hardware.
	USB 3.0 Experience Fastest data transfers at 5 Gbps with USB 3.0--the new latest connectivity standard. Built to connect easily with next-generation components and peripherals, USB 3.0 transfers data 10X faster and backward compatible with previous USB 2.0 components.
	PCIe 3.0 PCIe 3.0 is the ubiquitous and general-purpose PCI Express I/O standard. At 8GT/s bit rate, the interconnect performance bandwidth is doubled over PCIe 2.0, while preserving compatibility with software and mechanical interfaces.
	Dual DDR4 The primary advantages of DDR4 over DDR3, include higher module density, lower voltage requirements, coupled with higher data transfer rate.
	Moistureproof of PCB The popularity of PC usage and working environment is getting deteriorating and moist (rural, coastal, etc.). The PCB will be oxidizing easily by damp or absorbed moisture, and ionic migration or CAF (Conductive Anodic Filament) will be generated. Moisture-proof PCB meets high density and high reliability requirements for moisture proof.
	Low RdsOn P-Pak MOS Low resistance design can significantly reduce the current out of energy loss. Low temperature, small size, excellent thermal conductivity.
	USB Power Engine USB POWER Engine supports SATA power interface with ultra-high load of USB connectors and offers sufficient power to the system for stable operating.
	100% Solid Caps With armor-plated Biostar Technology, all capacitors are placed with 100% solid capacitors that have a lasting life cycle, durability and stability for crucial components.
	Super Anti-Surge Protection BIOSTAR exclusive Anti-Surge design provides the best protection of board and extends the product life. Having the latest model of "Transient Voltage Suppressor" on- board can effectively protect the board circuit, reducing the shocks caused by ESD as well as other damages arising from overvoltage transients to enhance system durability.

	Super LAN Surge Protection Super LAN Surge Protection, providing LAN port with more advanced antistatic protection capabilities by adding an integrated chip to strengthen electrical stability and prevent damage from lightning strikes and electrical surges. SLSP (Super LAN Surge Protection) series motherboard upgrades the existing system protection standards with maximum 4X protection comparing to other board makers.
	Nano Carbon Coating Heatsink Nano carbon coating heatsink enlarges the heat dissipation area to increase heat conductivity efficiently, compared to the aluminum-extruded heatsink.
	ESD Protection ESD (Electrostatic Discharge) is the major factor to destroy the PC by electrical overstress (EOS) condition. ESD occurred by PC users when touch any devices connect to a PC, which may result in damage to the motherboard or parts. ESD protection is designed to protect the motherboard and equipment from damage by EOS.
	USB Polyswitch On board dedicated power fuse to help prevent USB port failure. It prevents USB Port overcurrent and safe guard your system and device lifespan.
	BIOS Virus Protection When enabled, the BIOS will protect the boot sector and partition table by halting the system and flashing a warning message whether there's an attempt to write to these areas.
	OC / OV / OH Protection OC / OV / OH Protection design detects overvoltage conditions and prevents voltage surges from spreading in real time. It also actively cuts off the overvoltage supply to protect your system.
	UEFI BIOS Unified Extensible Firmware Interface (UEFI) is a brand new framework that provides a revolutionary interface. It is a modern clear and easy-to-use graphical user interface. The UEFI comes with a colorful easy-understand icons leads users into the setup layer directly.
	Header Zone Users can easily assemble their own computer, a simple-swap data discs and other accessories.

*The specification and pictures are subject to change without notice and the package contents may differ by

area or your motherboard version!